

**Patent**  
**09/697,619**

IN THE CLAIMS

Please cancel Claims 1-10 without prejudice and without disclaimer of subject matter.

Please add Claims 11-26 as indicated on the following Summary Sheet.

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CLAIM SUMMARY

Claims 1-10 (CANCELLED).

11. (new) A bracket for mounting an electrical component device comprising:  
a first end, said first end having a substantially semi-circular shape and an inner and outer surface, whereby said inner surface and said substantially semi-circular shape permit an electrical component device, having a body portion and leads extending from the body portion, to be retained thereon;

a second end; and

a shaft connecting said first and second ends, said shaft having at least one mounting point for attaching said bracket to a mounting surface,

wherein the body portion of the electrical component device is removably retained within said first end, and

further wherein upon attaching said bracket to the mounting surface the body portion of the electrical component device does not contact the mounting surface on which said bracket is attached.

12. (new) The bracket of claim 11 wherein the leads extending from the body portion of the electrical component device are electrically connected to the mounting surface.

13. (new) The bracket of claim 11 wherein the electrical component device is a photodiode.

14. (new) The bracket of claim 11 wherein the electrical component device is a laser.

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15. (new) The bracket of claim 11 wherein said shaft and said first and second ends are comprised of aluminum.

16. (new) The bracket of claim 11 wherein said shaft forms a right angle whereby said second end and said at least one mounting point are disposed 90 degrees relative to said first end.

17. (new) The bracket of claim 11 wherein the mounting surface comprises a plug in circuit board.

18. (new) The bracket of claim 11 wherein the mounting surface comprises a Trans-Impedance-Amplifier.

19. (new) A method for mounting an electrical component device comprising the steps of:

mounting an electrical component device, having a body portion and leads extending from the body portion, on a mounting bracket, said bracket having a first end, the first end having a substantially semi-circular shape and an inner surface and an outer surface, wherein the inner surface and substantially semi-circular shape permit the electrical component device to be removably retained thereon, a second end and a shaft connecting the first and second ends; and attaching said mounting bracket at the mounting point to a mounting surface;

wherein upon attaching said mounting bracket to the mounting surface, the body portion of the electrical component device contacts only the mounting bracket and does not contact the mounting surface on which said mounting bracket is attached.

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20. (new) The method of claim 19 further comprising the step of electrically connecting the leads extending from the body portion of the electrical component device to the mounting surface.
21. (new) The method of claim 19 wherein the electrical component device is a photodiode.
22. (new) The method of claim 19 wherein the electrical component device is a laser.
23. (new) The method of claim 19 wherein said shaft and said first and second ends are comprised of aluminum.
24. (new) The method of claim 19 wherein said shaft forms a right angle whereby said second end and said at least one mounting point are disposed 90 degrees relative to said first end.
25. (new) The method of claim 19 wherein the mounting surface comprises a plug in circuit board.
26. (new) The method of claim 19 wherein the mounting surface comprises a Trans-Impedance-Amplifier.